

## RoHS Compliant



### **Description:**

MLCC consists of a conducting material and electrodes. To manufacture a chip-type SMT and achieve miniaturization, high density and high efficiency, ceramic condensers are used. 0201 MLCC is performed by high precision technology achieve high capacitance in unit size and ensure the stability and reliability of products.

### Features:

- · High capacitance in unit size.
- · High precision dimensional tolerances.
- Suitable used in high-accuracy automatic mounting machine.

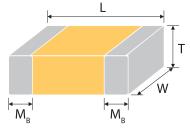
### **Applications:**

- · Miniature microwave module.
- Portable equipments (ex. Mobile phone, PDA).
- · High frequency circuits.

### **How To Order:**

МС	31	Х	225	K	100	С	Т
MC	<u>Size</u>	Dielectric	<u>Capacitance</u>	<u>Tolerance</u>	Rated Voltage	<u>Termination</u>	Packaging style
Multicomp	Inch (mm) 0201 (0603)	N=NP0 (C0G) B=X7R X=X5R	Two significant digits followed by no. of zeros. And R is in place of decimal point.  Eg.:  0R5 = 0.5pF  1R0 = 1.0pF  102 = 10x10 <sup>2</sup> = 1,000pF	A=±0.05pF B=±0.1pF C=±0.25pF D=±0.5pF F=±1% G=±2% J=±5% K=±10% M=±20% Z=-20/+80%	Two significant digits followed by no. of zeros. And R is in place of decimal point.  6R3=6.3V DC 100=10V DC 160=16V DC 250=25V DC 500=50V DC	C=Cu/Ni/Sn	T = 7" reeled

### **External Dimensions:**



The outline of MLCC

Size Inch (mm)	L (mm)	W (mm)	T max (mm)/Symbol		M <sub>B</sub> (mm)
0204 (0602)	0.6 ±0.03	0.30±0.03	0.3 ±0.03		0.45 +0.05
0201 (0603)	0.6 ±0.05 <sup>#1</sup>	0.3±0.05 <sup>#1</sup>	0.3 ±0.05 <sup>#1</sup>	-	0.15 ±0.05

<sup>\*</sup> Reflow soldering only. #1 For 0201/Cap≧0.68uF

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### **General Electrical Data:**

Size	0201					
Dielectric	NP0	X7R	X5R			
Capacitance*	0.1pF to 120pF	100pF to 10nF	100pF to 1µF			
Capacitance tolerance**	Cap≤5pF <sup>#1</sup> :  A (±0.05pF), B (±0.1pF), C	J (±5%), K (±10%), M (±20%)	J (±5%),K (±10%), M (±20%)			
Rated voltage (WVDC)	16V, 25V, 50V	6.3V, 10V, 16V, 25V, 50V	6.3V, 10V, 16V, 25V, 50V			
Tan δ / Q*	Cap<30pF, Q≥400+20C Cap≥30pF, Q≥1000	Note 1				
Insulation resistance at Ur	≥10GΩ	≥10GΩ or RxC≥500ΩxF whichever is less				
Operating temperature	-55 to	+125°C	-55 to +85°C			
Capacitance change	±30ppm	±30ppm ±15%				
Termination	Ni/Sn (lead-free termination)					

<sup>#1:</sup> NP0, 0.1pF product only provide B tolerance

NP0: Apply 1.0±0.2Vrms, 1.0MHz±10% at the condition of 25°C ambient temperature.

X7R, X5R: Apply 1.0±0.2Vrms, 1.0kHz±10%(0201/6.3V,Cap≥224 : 0.5±0.2Vrms, 1.0kHz±10%) at the condition of 25°C ambient temperature.

Note 1: X7R/X5R

Rated vol.	D.F.	Exception of D.F.			
≥50V	≤3%	-			
25V	≤3.5%	≤5%	0201≥0.01µF		
16V	≤3.5%	≤5%	0201≥0.01µF		
10V	≤5%	≤10%	0201≥0.012µF		
100	≥5%	≤15%	0201≥0.1µF		
6.3V	≤10%	≤15%	0201≥0.1µF		

<sup>\*</sup> Measured at 30~70% related humidity.

<sup>\*\*</sup> Preconditioning for Class II MLCC: Perform a heat treatment at 150±10°C for 1 hour, then leave in ambient condition for 24±2 hours before measurement.



## **Packaging Dimension And Quantity:**

Size	Thickness (s	mm\/Symbol	Paper tape		
Size	Size Thickness (r		7" reel		
0204 (0602)	0.3 ±0.03	1	15,000	70,000	
0201 (0603)	0.3 ±0.05 <sup>#1</sup>	L	15,000	-	

Unit: pieces

### **Reliability Test Conditions and Requirements:**

No	Item	т	est Condition	Requirements				
1	Visual and Mechanical	-		No remarkable defect. Dimensions to conForm to individual specification sheet.				et.
2	Capacitance			Shall not exce	ed the limits	given in th	he detailed spec.	
		Class I: NP0		NP0: Cap≥30 X7R, X5R:	pF, Q≥1000;	Cap<30pF	F, Q≥400+20C	
			1.0±0.2Vrms, 1MHz±10%	Rated vol.	D.F	Exc	eption of D.F.	
	Q/ D.F.	Cap>1000pF,	1.0±0.2Vrms, 1KHz±10%	≥50V	≤3%	-		
3	(Dissipation	Class II: X7R	, X5R 1kHz±10%**	25V	≤3.5%	≤5%	0201≥0.01µF	
	Factor)		s, 1.0kHz±10% : 0201	16V	≤3.5%	≤5%	0201≥0.01µF	
		≥0.22 uF(6.3\	V)	10)/	<b>/</b> E0/	≤10%	0201≥0.012µF	
				10V	≤5%	≤15%	0201≥0.1µF	
				6.3V	≤10%	≤15%	0201≥0.1µF	
4	Dielectric Strength	Duration: 1 to	age (≤100V) 250%. o 5 sec. discharge current less than	No evidence of	of damage o	r flash ove	r during test.	
	Insulation			≥10GΩ or Rx0 Class II (X5R,			s smaller.	
5	Resistance	I to apply rated voltage for may 120sec.		Rated voltag	е	Insulation	n resistance	
				6.3V; 10V:0201≥47nF		≥100 Ω-F		
		With no elect	rical load.		1			
		T.C.	Operating Temp	T.C.	<del></del>	tance Change		
6	Temperature	NP0 (C0G)	55~125°C at 25°C	NP0 (C0G) X7R		Within ±30ppm/°C		
	Coefficient	X7R	X7R 55~125°C at 25°C		Within ±15%			
		X5R	25~85°C at 20°C	X5R	Within ±1	5%		
7.	Adhesive Strength of Termination	Pressurizing to Test time: 10:		No remarkabl	e damage or	removal c	of the terminations	





No	Item	-	Test Condition		Requirements	
8	Vibration Resistance	Vibration frequency: 10~55 Hz/min. Total amplitude: 1.5mm Test time: 6 hrs. (Two hrs each in three mutually perpendicular directions.) Measurement to be made after keeping at room temp. for 24±2 hrs.		n three s.)	No remarkable damage. Cap change and Q/D.F.: To meet initial spec.	
9	Solderability	Solder temporal Dipping time	erature: 235±5°C : 2±0.5 sec.		95% min. coverage of all metalized area	
10	Bending Test	The middle part of substrate shall be pressurized by means of the pressurizing rod at a rate of about 1mm per second until the deflection becomes: 5mm and then the pressure shall be maintained for 5±1 sec.  Measurement to be made after keeping at room temp. for 24±2 hrs.			No remarkable damage. Cap change: NP0: within ±5.0% or ±0.5pF whichever is larger. X7R, X5R: within ±12.5% Y5V: within ±30% (This capacitance change means the change of capacitance under specified flexure of substrate from the capacitance measured before the test.)	
11	Resistance to Soldering Heat	Solder temperature: 260±5°C Dipping time: 10±1 sec Preheating: 120 to 150°C for 1 minute before immerse the capacitor in a eutectic solder. Before initial measurement (Class II only): Perform 150+0/-10°C for 1 hr and then set for 24±2 hrs at room temp. Measurement to be made after keeping at room temp. for 24±2 hrs.		or in a ss II 1 hr and mp.	No remarkable damage. Cap change: NP0: within ±2.5% or ±0.25pF whichever is larger. X7R, X5R: within ±7.5% Y5V: within ±20% Q/D.F., I.R. and dielectric strength: To meet initial requirements. 25% max. leaching on each edge.	
			five cycles accordir ures and time.	ng to		
		Step	Temp. (°C)	Time (min.)	No remarkable damage.	
		1 Min. c	perating temp. +0/-3	30±3	Cap change:	
12	Temperature	2 Room	temp.	2~3	NP0: within ±2.5% or ±0.25pF whichever is larger. X7R, X5R: within ±7.5%	
'4	Cycle		operating temp. +3/-0	30±3	Y5V: within ±20%	
			temp.	2~3	Q/D.F., I.R. and dielectric strength: To meet initial	
		Before initial measurement (Class II only): Perform 150+0/-10°C for 1 hr and then set for 24±2 hrs at room temp. Measurement to be made after keeping at room temp. for 24±2 hrs.		en set	requirements.	





No	Item	Test Condition	Requirements			ts
13	Humidity (Damp Heat)	Test temp.: 40±2°C Humidity: 90~95% RH Test time: 500+24/-0hrs. Before initial measurement (Class II only): Perform 150+0/-10°C for 1 hr and	No remarkable damage.  Cap change : NP0: within ±5.0% or ±0.5pF whichever is larger.  X7R, X5R: ≥10V, within ±12.5%,  10V ≥ 0.1μF, within ±25%; 6.3V, within ±25%  Y5V: ≥10V, within ±30% 6.3V, within ±30/-40%  Q/D.F. value:  NP0: Cap≥30pF, Q≥350; 10pF≤Cap<30pF, Q≥275+2.5C  Cap<10pF; Q≥200+10C  X7R, X5R:			
	Steady State	then set for 24±2 hrs at room temp	Rated vol. ≥50V	D.F ≤6%	_ EXC	eption of D.F.
		Measurement to be made after keeping at room temp. for 24±2 hrs.	25V	±5% ≤5%	≤10%	0201≥0.01µF
			16V	≤5%	≤15%	0201≥0.01µF
			10V	≤7.5%	≤15%	0201≥0.012µF
			100	27.570	≤20%	0201≥0.1µF
			6.3V	≤15%	≤30%	0201≥0.1μF
			I.R.: ≥10V, ≥1GΩ or RxC≥50Ω-F whichever is smaller. 6.3V; 10V:0201≥47nF, RxC≥10Ω-F			
	Humidity	Test temp.: 40±2°C Humidity: 90~95%RH Test time: 500+24/-0 hrs. To apply voltage : rated voltage	Q/D.F. value:	NP0: within ±7 (7R, X5R: ≥′ (10V≧ 0.1µF, 6.3V, within ± ′5V: ≥10V, w 6.3V, wi	10V, within within ±25 :25% ithin ±30% thin +30/-4	%;
14	(Damp Heat)	Before initial measurement (Class II only): To apply test voltage for 1hr at	Rated vol.	D.F	Exc	eption of D.F.
	Load	40°C and then set for 24±2 hrs at room	≥50V	≤6%	-	
		temp.  Measurement to be made after keeping	25V	≤5%	≤10%	0201≥0.01µF
		at room temp. for 24±2 hrs.	16V	≤5%	≤15%	0201≥0.01µF
			10V	≤7.5%	≤15%	0201≥0.012µF
			6.2)/	<1E0/	≤20%	0201≥0.1µF
				≤15% 0MΩ or RxC V:0201≥47nf		0201≥0.1μF lichever is smaller. -F

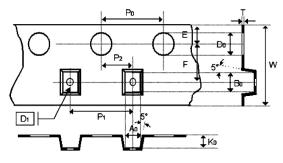




No	Item	Test Condition	Requirements			ts
	High	Test temp.: NP0, X7R: 125±3°C X5R,Y5V: 85±3°C To apply voltage: 1) Cap.≥0.1uF: 100% of rated voltage 2) 6.3V: 150% of rated voltage. 3) >6.3V: 200% of rated voltage. Test time: 1,000+24/-0 hrs. Before initial measurement (Class II only): To apply test voltage for 1hr at test temp. and then set for 24±2 hrs at	No remarkable damage. Cap change: NP0: within $\pm 3.0\%$ or $\pm 0.3$ pF whichever is larger. X7R, X5R: $\geq 10$ V, within $\pm 12.5\%$ , $10$ V $\geq 0.1$ µF, within $\pm 25\%$ ; $6.3$ V, within $\pm 25\%$ Y5V: $\geq 10$ V, within $\pm 30\%$ $6.3$ V, within $\pm 30$ /-40% Q/D.F. value: NP0: Cap $\geq 30$ pF, Q $\geq 350$ ; $10$ pF $\leq Cap<30$ pF, Q $\geq 275+2.5$ C Cap< $10$ pF; Q $\geq 200+10$ C X7R/X5R:			
15	Temperature Load	Load Measurement to be made after keeping	Rated vol.	D.F	Exc	eption of D.F.
	(Endurance)		≥50V	≤6%	-	
			25V	≤5%	≤10%	0201≥0.01µF
			16V	≤5%	≤15%	0201≥0.01µF
			10V	≤7.5%	≤15%	0201≥0.012µF
			100	≥7.5%	≤20%	0201≥0.1µF
			6.3V	≤15%	≤30%	0201≥0.1µF
			·	GΩ or RxC≥ V:0201≥47nl		chever is smaller. Ω-F

### **Appendixes**

Tape & Reel Dimensions



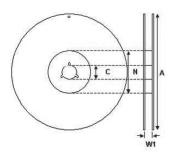
The dimension of plastic tape

Size	0201
Thickness	L
A <sub>0</sub>	0.38±0.05
Bo	0.68±0.05
Т	0.42±0.05
K <sub>0</sub>	-
W	8.00±0.10
P <sub>0</sub>	4.00±0.10
10xP₀	40.0±0.10
P <sub>1</sub>	2.00±0.05
P <sub>2</sub>	2.00±0.05
D <sub>0</sub>	1.55±0.05
D <sub>1</sub>	-
E	1.75±0.05
F	3.50±0.05

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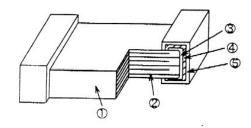




Size	0201			
Reel size	7"	13"		
С	13 +0.5/-0.2	13 +0.5/-0.2		
W1	8.4 +1.5/-0	8.4 +1.5/-0		
Α	178 ±0.10	330 ±1		
N	60 +1/-0	100 ±1		

The dimension of reel

### **Constructions:**



No.	Na	me	NPO, X7R, Y5V	
1	Ceramic	material	BaTiO₃ based	
2	Inner electrode		Ni	
3		Inner layer	Cu	
4	Termination	Middle layer	Ni	
5		Outer layer	Sn (Matt)	

### Storage and handling conditions

- (1) To store products at 5°C to 40°C ambient temperature and 20 to 70%. related humidity conditions.
- (2) The product is recommended to be used within one year after shipment. Check solderability in case of shelf life extension is needed.

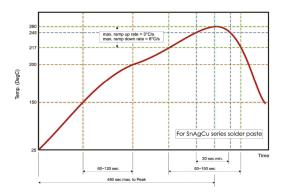
### Cautions:

- a. The corrosive gas reacts on the terminal electrodes of capacitors, and results in the poor solderability. Do not store the capacitors in the ambience of corrosive gas (e.g., hydrogen sulfide, sulfur dioxide, chlorine, ammonia gas etc.)
- b. In corrosive atmosphere, solderability might be degraded, and silver migration might occur to cause low reliability.
- c. Due to the dewing by rapid humidity change, or the photochemical change of the terminal electrode by direct sunlight, the solderability and electrical performance may deteriorate. Do not store capacitors under direct sunlight or dewing condition. To store products on the shelf and avoid exposure to moisture.

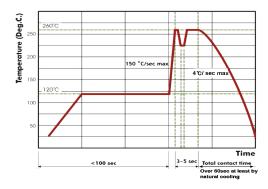


### **Recommended Soldering Conditions:**

The lead-free termination MLCCs are not only to be used on SMT against lead-free solder paste, but also suitable against lead-containing solder paste. If the optimized solder joint is requested, increasing soldering time, temperature and concentration of  $N_2$  within oven are recommended.



Recommended reflow soldering profile for SMT process with SnAgCu series solder paste.



Recommended wave soldering profile for SMT process with SnAgCu series solder.

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